

Product Compliance Declaration

Please see www.molex.com for the most up-to-date information.

Contact Information

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Part Information

Part Number 0353181420 **Part Weight** 4.235028G

Part Name MINIFIT HDER WO EARS 14CK 353181420

Product Composition

Name	Type	CAS Number	Proportion (% Total)	Mass (Grams)
MINIFIT HDER WO EARS 14CK 353181420	Assembly		100	4.235028
NEW MINIFIT CONN R/A WAFE	Component		35.2064	1.491
PA66 NATURAL	Material		35.2064	1.491
PA66	Substance		33.4461	1.41645
Further Additives, not to declare	Substance	system	1.7603	0.07455
1.07 SQ WIRE PIN(PLATED)	Assembly		24.6283	1.043014
1.07 SQ WIRE PIN	Assembly		24.6279	1.043
1.07 SQ WIRE PIN	Component		24.6279	1.043
C2700	Material		24.6279	1.043
Copper	Substance	7440-50-8	16.0082	0.67795
Zinc (metal)	Substance	7440-66-6	8.6075	0.364529
Lead	Substance	7439-92-1	0.0062	0.000261
Iron	Substance	7439-89-6	0.0062	0.000261

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Limitation of this Product Compliance Declaration: This declaration is based on the state of knowledge and belief of Molex as of the date that it is provided. Molex bases its knowledge and belief on information provided by numerous sources, including third parties, and in certain circumstances laboratory test results. Molex has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and substances. Molex represents that to the best of its knowledge that the information provided in this declaration is accurate. Molex's sole liability shall be to either replace the product or refund the purchase price of the product if it does not meet the requirement of this declaration.

Name	Type	CAS Number	Proportion (% Total)	Mass (Grams)
Copper Plating	Material		0.0002	0.000007
Copper	Substance	7440-50-8	0.0002	0.000007
Tin Plating	Material		0.0002	0.000007
Tin	Substance	7440-31-5	0.0002	0.000007
1.07 SQ WIRE PIN(PLATED)	Assembly		40.1654	1.701014
1.07 SQ WIRE PIN(UNPLATE	Assembly		40.165	1.701
1.07 SQ WIRE PIN(UNPLATE	Component		40.165	1.701
C2700	Material		40.165	1.701
Copper	Substance	7440-50-8	26.1073	1.10565
Zinc (metal)	Substance	7440-66-6	14.0377	0.5945
Lead	Substance	7439-92-1	0.01	0.000425
Iron	Substance	7439-89-6	0.01	0.000425
Copper Plating	Material		0.0002	0.000007
Copper	Substance	7440-50-8	0.0002	0.000007
Tin Plating	Material		0.0002	0.000007
Tin	Substance	7440-31-5	0.0002	0.000007

ROHS Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

Contained Substances Exceeding Threshold

None

Exemptions

None

REACH-SVHC Declaration Information

Regulatory Revision D(2020)9139-DC (19 Jan 2021)

Contained Substances Exceeding Threshold

None

GADSL Declaration Information

Regulatory Revision GADSL imported from IMDS

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
lead		*Note	500	Yes
lead	C2700	*Note	250	Yes
copper	C2700	*Note	650,000	Yes
copper	e-plate Cu (electrodeposited Copper Coatings)	*Note	999,625	Yes

*Note: For GADSL substance declarable/prohibited threshold values, please reference <http://www.gadsl.org/>

Exemptions

Part Name	Exemption
	44 Concentration within acceptable GADSL limits
C2700	44 Concentration within acceptable GADSL limits


HFLH Declaration Information

Regulatory Revision IEC 61249-2-21

Contained Substances Exceeding Threshold

None

China ROHS Declaration Information

Part Number 0353181420		Hazardous Substances				
Part Name MINIFIT HDER WO EARS 14CK 353181420						
Part Information						
Components	Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
MINIFIT HDER WO EARS 14CK 353181420	O	O	O	O	O	O
NEW MINIFIT CONN R/A WAFE	O	O	O	O	O	O
1.07 SQ WIRE PIN(PLATED)	O	O	O	O	O	O
1.07 SQ WIRE PIN	O	O	O	O	O	O
1.07 SQ WIRE PIN	O	O	O	O	O	O
1.07 SQ WIRE PIN(PLATED)	O	O	O	O	O	O
1.07 SQ WIRE PIN(UNPLATE	O	O	O	O	O	O
1.07 SQ WIRE PIN(UNPLATE	O	O	O	O	O	O

Process Information

Component Plating / Surface Finish	SnCu
Termination Base Alloy	Brass
Solder Alloy	SnAgCu
Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A
Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

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